



Material Content Data Sheet



Sales Product Name		BSZ215C H		Issued		19. January 2018		
MA#		MA001298710						
Package		PG-TSDSON-8-30		Weight*		32.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.03		271	
	noble metal	gold	7440-57-5	0.034	0.11		1052	
	inorganic material	silicon	7440-21-3	0.283	0.87	1.01	8709	10032
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		108	
	non noble metal	zinc	7440-66-6	0.014	0.04		434	
	non noble metal	iron	7439-89-6	0.282	0.87		8680	
	non noble metal	copper	7440-50-8	11.466	35.24	36.16	352436	361658
wire	non noble metal	copper	7440-50-8	0.193	0.59	0.59	5922	5922
encapsulation	organic material	carbon black	1333-86-4	0.039	0.12		1193	
	plastics	epoxy resin	-	1.998	6.14		61422	
	inorganic material	silicondioxide	60676-86-0	17.364	53.38	59.64	533711	596326
leadfinish	non noble metal	tin	7440-31-5	0.388	1.19	1.19	11933	11933
plating	noble metal	silver	7440-22-4	0.460	1.41	1.41	14129	14129
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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